



Product Change Notification

Change Notification #: 115569 - 00
Change Title: Intel® Thermal Solution BXTS13X, PCN 115569-00, Product Design, Documentation, Replace (TIM) Thermal Interface Material Packets with Pre-Applied Thermal Material

Date of Publication: June 14, 2017

Key Characteristics of the Change:

Product Design, Documentation

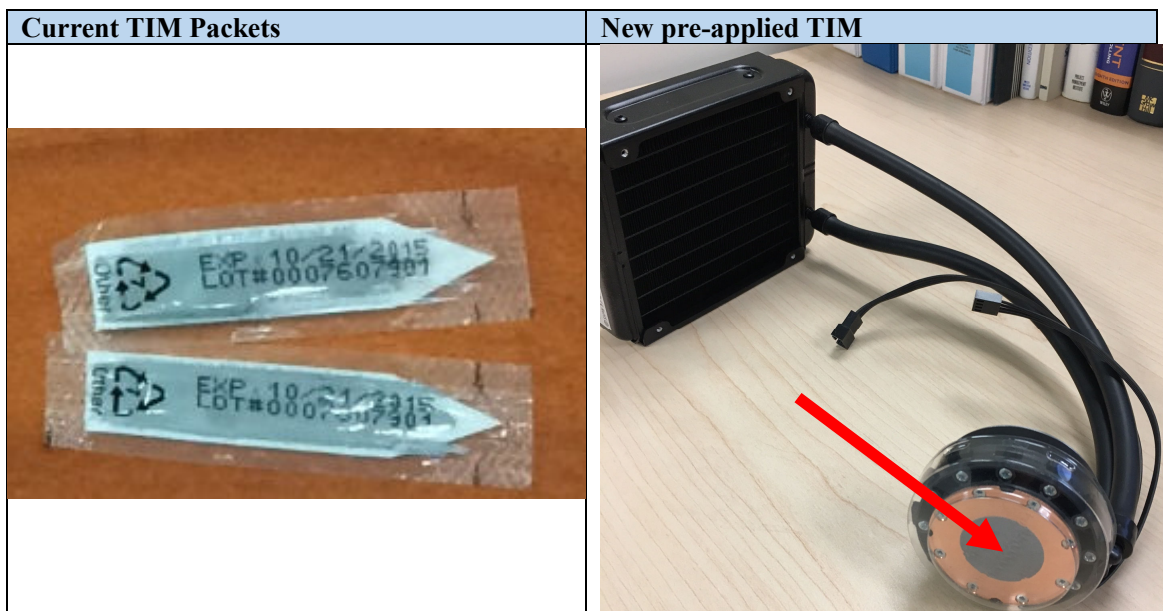
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	July 14, 2017
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Description of Change to the Customer:

Intel Corporation is implementing a change to the Intel® Thermal Solution BXTS13X. The two green (TIM's) Thermal Interface Material packets will be replaced by a pre-applied Thermal Material directly to the base of the heatsink. To support this change, the Warranty Booklet instructions will change to reflect the pre-applied TIM. Please reference the images of changes provided below.

- The TIM packets will be replaced with the pre-applied TIM material:



Customer Impact of Change and Recommended Action:

The thermal solution is a visible change since the TIM will now be pre-applied to the base of the heat sink. The Warranty Booklet instructions will change to reflect the pre-applied TIM. There are no other changes to the factory packaging.

Customers may see mixed product until current inventory has been completely depleted.

This change will meet or exceed thermal performance expectations.

Please contact your local Intel Sales Representative should you have questions regarding this change.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Thermal Solution BXTS13X	BXTS13X929672	929672

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 14, 2017	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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